

**In the Claims:**

Please cancel claims 1, 5-6, 11, and 13. Please amend claims 2-4, 7, 9-10, and 12. Please add new claims 27-38. The claims are as follows:

1. (Cancelled)

2. (Currently amended) The method of claim [[1]] 3, wherein the first dimension of the elongated non-circular openings is greater than the second dimension of the non-circular openings, and wherein the non-circular openings are in a plane parallel to a top surface of the second substrate.

3. (Currently amended) The method of claim 1 A method of forming an integrated chip package, comprising the steps of:

providing a first substrate and a second substrate, each having conductive pads thereon;  
applying a mask to at least one of the first and second substrates, wherein the mask has a plurality of non-circular openings having a first dimension and a second dimension, such that the conductive pads are not covered by the mask in the direction of the first dimension and partially covered by the mask in the direction of the second dimension; and

providing a reflowable material between the conductive pads of the first and second substrates, wherein the first dimension of the non-circular openings is selectively oriented in the direction of highest stress for each interconnection formed from the reflowable material within the integrated chip package.

4. (Currently amended) The method of claim [[1]] 3, whercin the non-circular openings of the mask are elliptical.

5-6. (Canceled)

7. (Currently amended) The method of claim [[1]] 3, whcrein the mask comprises a non-wettable material.

8. (Original) The method of claim 7, wherein the mask comprises an epoxy.

9. (Currently amended) The method of claim [[1]] 3, whcrein the first substrate is a chip carrier.

10. (Currently amended) The method of claim [[1]] 3, whcrein the second substrate is a printed circuit board.

11. (Canceled)

12. (Currently amended) The method of claim [[1]] 3, wheren a plurality of traces are mounted between the non-circular openings of the mask.

13. (Canceled)

14-26. (Cancelled)

27. (New) An method of forming an integrated chip package, comprising:
- providing a first substrate;
- providing a second substrate having a plurality of circular conductive pads formed thereon with a mask covering the second substrate and portions of said pads with a plurality of interconnections formed between the first substrate and the pads formed on the second substrate, said mask having a plurality of non-circular openings having an oblong shape, an oval shape, or an elliptical shape,
- wherein the openings have a first dimension and second dimension in a plane parallel to a top surface of the second substrate, and
- wherein the first dimension is greater than the second dimension and is larger than a diameter of the pads and the second dimension is smaller than the diameter, with the first dimension selectively oriented on the pad in a direction of highest stress within each interconnection.
28. (New) The method of claim 27, wherein the openings have the oblong shape.
29. (New) The method of claim 27, wherein the openings have the oval shape.
30. (New) The method of claim 27, wherein the openings have the elliptical shape.

31. (New) The method of claim 27, further comprising a plurality of traces mounted between the openings of the mask.

32. (New) The method of claim 27, wherein the mask comprises a non-wettable material.

33. (New) The method of claim 27, wherein the mask comprises an epoxy.

34. (New) The method of claim 27, wherein the first substrate is a chip carrier, and wherein the second substrate is a printed circuit board.

35. (New) The method of claim 27, wherein the first substrate is a chip carrier.

36. (New) The method of claim 27, wherein the second substrate is a printed circuit board.

37. (New) The method of claim 27, further comprising forming interconnections within the openings of the mask.

38. (New) The method of claim 37, wherein the interconnections are solder balls that wet only to an area of the conductive pads exposed by the openings in the mask.